

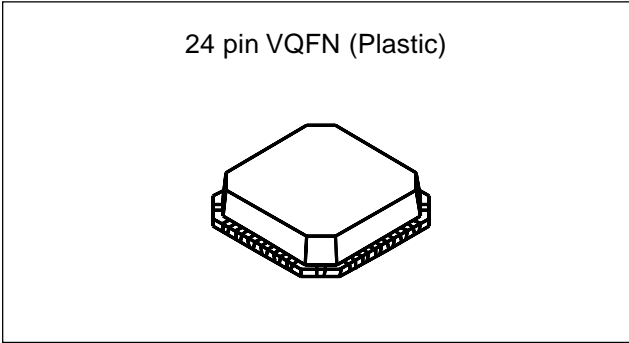
**Analog Signal Processor TX-IF IC for W-CDMA Cellular Phones**

**Description**

The CXA3309ER is an analog signal processor TX-IF IC for the W-CDMA cellular phones. This IC contains voltage-controlled gain control amplifier and quadrature modulator.

**Features**

- Gain control amplifier with a linear and wide gain variable range
- I-Q quadrature modulator
- Power saving switch
- Low voltage operation (2.7 to 3.3V)
- Small package (24-pin VQFN)



**Applications**

Analog signal processor TX-IF IC for the W-CDMA cellular phones

**Absolute Maximum Ratings**

• Supply voltage	Vcc	-0.3 to +5.5	V
• Operating temperature	Topr	-55 to +125	°C
• Storage temperature	Tstg	-65 to +150	°C

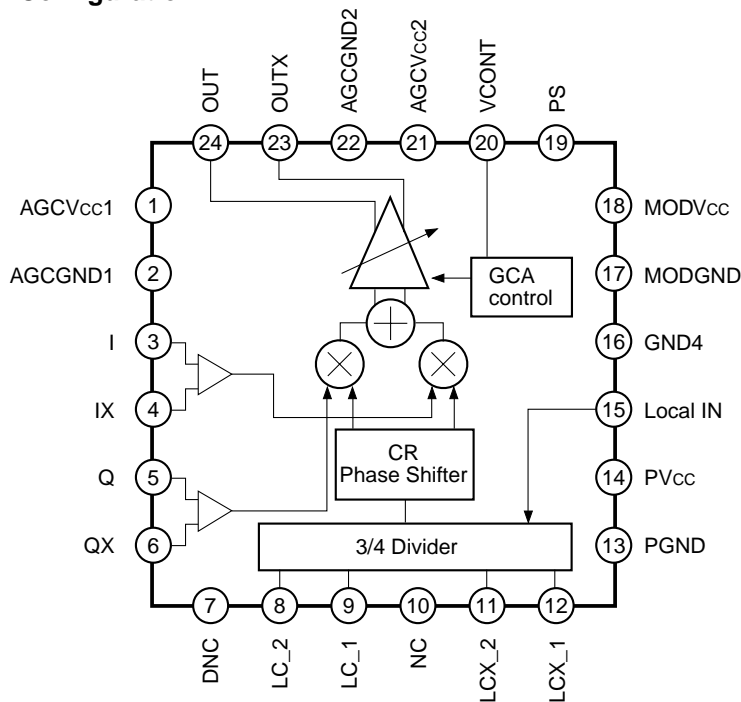
**Recommended Operating Conditions**

• Supply voltage	Vcc	2.7 to 3.3	V
• Operating temperature	Ta	-25 to +85	°C

**Structure**

Bipolar silicon monolithic IC

**Block Diagram and Pin Configuration**



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Pin Description

Pin No.	Symbol	Typical pin voltage [V]	Equivalent circuit	Description
1	AGCV <sub>cc</sub> 1	2.85		Positive power supply.
2	AGCGND1	0		Ground.
3 4 5 6	I IX Q QX	—		I, Q inputs. Applies a bias voltage from the external source.
7	DNC	—		Don't connect.
8 9 11 12	LC_2 LC_1 LCX_2 LCX_1	2.25		Resonance filter. Forms a resonance filter by attaching the external LC parallel circuit.
10	NC	—		Not connect.
13	PGND	0		Ground.
14	PV <sub>cc</sub>	2.85		Positive power supply.
15	Local IN			Local input.

Pin No.	Symbol	Typical pin voltage [V]	Equivalent circuit	Description
16	GND4	0		Ground.
17	MODGND	0		Ground.
18	MODV <sub>cc</sub>	2.85		Positive power supply.
19	PS	—		Power saving mode switch input. High: Active mode Low: Power saving mode
20	VCONT	—		Gain control voltage input.
21	AGCV <sub>cc2</sub>	2.85		Positive power supply.
22	AGCGND2	0		Ground.
23 24	OUTX OUT	—		IF signal differential output.

## Input Conditions for Each Pin

Item	Symbol	Conditions	Pin No.	Min.	Typ.	Max.	Unit
I/Q bias voltage	VBIQ		3, 4, 5, 6	1.35	1.425	1.65	V
I/Q input voltage	VIQ	Differential input	3, 4, 5, 6	—	0.4	1	Vp-p
I/Q band width	BW <sub>IQ</sub>		3, 4, 5, 6	—	—	5	MHz
Local frequency	f <sub>LO</sub>		15	—	760	—	MHz
Local input level	LO		15	-18	-15	-12	dBm
PS voltage-High	V <sub>PSH</sub>		19	2.0		V <sub>CC</sub>	V
PS voltage-Low	V <sub>PSL</sub>		19	0		0.8	V
Control voltage range	V <sub>CN</sub>		20	0		V <sub>CC</sub>	V

## Electrical Characteristics

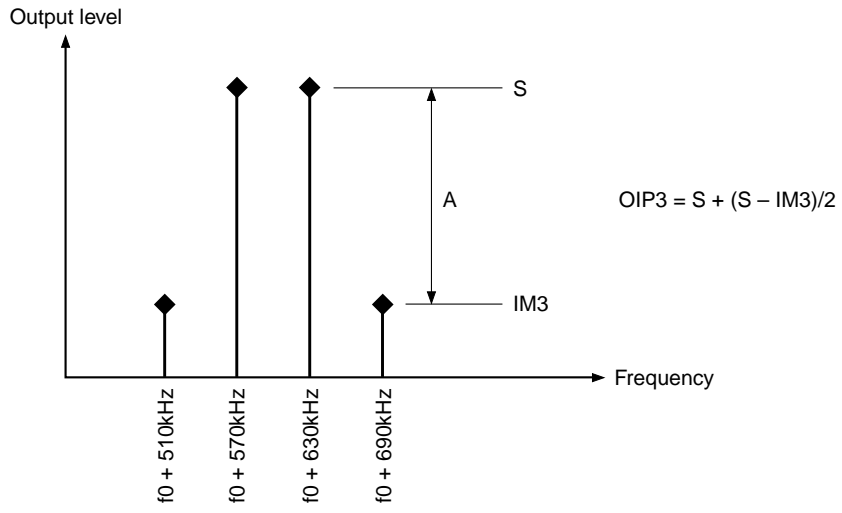
(V<sub>CC</sub> = 2.85V, T<sub>a</sub> = 27°C)

Item	Symbol	Conditions	Measurement point	Min.	Typ.	Max.	Unit
<b>DC Characteristics</b>							
Current consumption 1	I <sub>max</sub>	V <sub>CONT</sub> = 2.85V	A	21.5	32	43	mA
Current consumption 2	I <sub>min</sub>	V <sub>CONT</sub> = 0V	A	17.5	26	32.5	
Power saving current	I <sub>ps</sub>	PS = low (in power saving mode)	A	—	—	5	μA
<b>AC Characteristics</b>							
Output IP3	OIP3	Note1	B	8.5	—	—	dBm
Output power 1	P <sub>O1</sub>	V <sub>CONT</sub> = 2.3V, differential output, f = 570MHz	B	-19	-15	-11	dBm
Output power 2	P <sub>O2</sub>	V <sub>CONT</sub> = 0.3V, differential output, f = 570MHz	B	-83	-77	-73	
Gain control range	G <sub>cr</sub>	V <sub>CONT</sub> = 0.3 to 2.3V, f = 570MHz	B	54	62	70	dB
Output noise power 1	N <sub>O1</sub>	V <sub>CONT</sub> = 1.8V, I/Q inputs are no signal.	B	—	—	-147	dBm/ Hz
I, Q residual sideband product	I <sub>mg</sub>	Suppression ratio of desired signal (f = 570 + 1) MHz and image signal (f = 570 - 1) MHz	B	—	—	-25	dBc
Carrier leak	CL	Ratio of desired signal (f = 570 + 1) MHz and local leak (f = 570) MHz	B	—	—	-18	
Input I/Q phase error	I <sub>QPE</sub>	Input signal I/Q phase difference -90° when the output signal I/Q phase difference is 90°.	B	-3	0	3	deg
Input I/Q gain error	I <sub>QGE</sub>	I/Q input signal level difference when the output signal I/Q levels are the same.	B	-2.5	0	2.5	dB

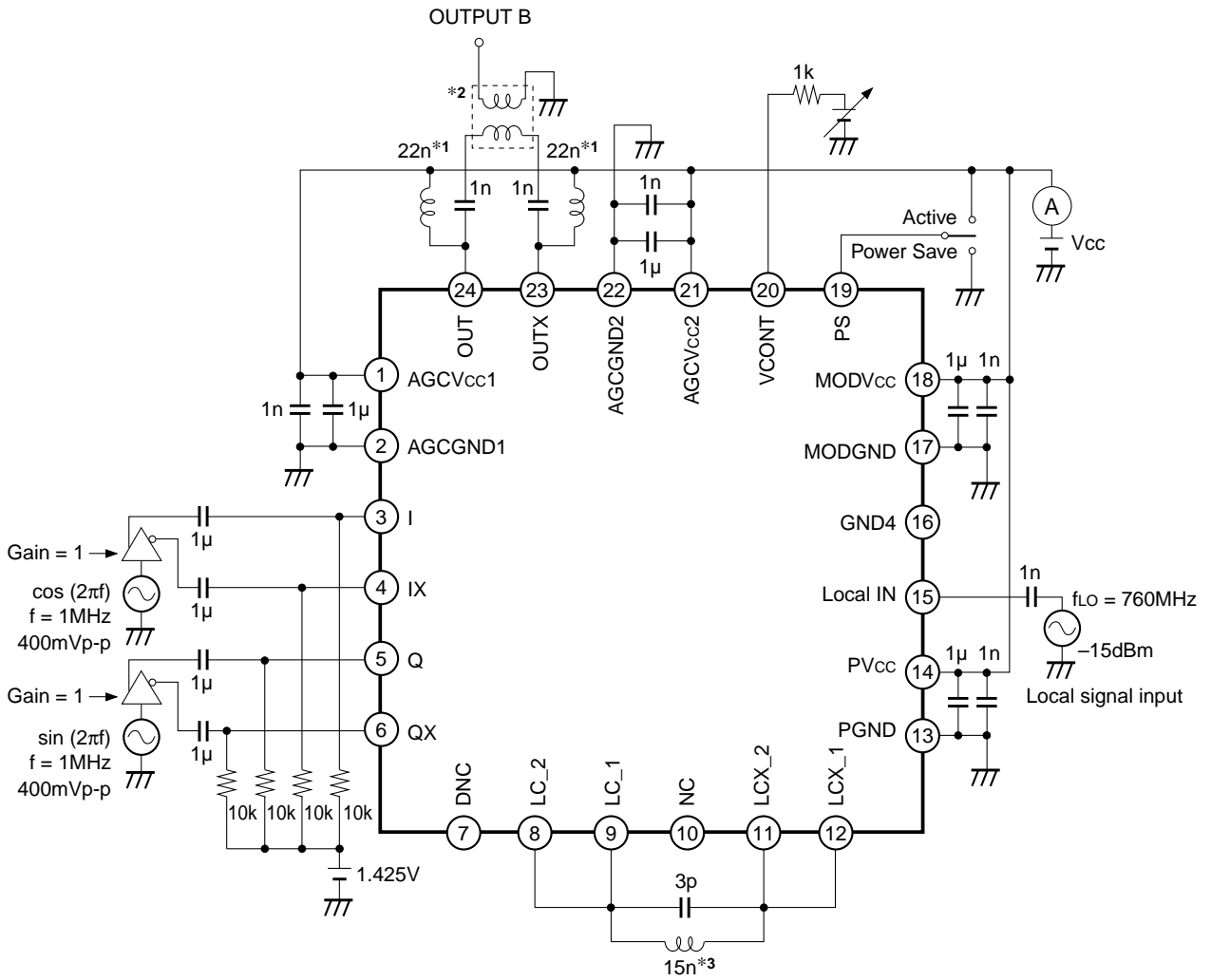
- Unless otherwise specified, the I/Q baseband input signals and local input signal use the conditions shown in the Electrical Characteristics Measurement Circuit and the control voltage and power saving pins are set to V<sub>CONT</sub> = 2.3V, PS = high.
- IF output impedance is 1kΩ.
- Set the L, C values between Pins 8, 9 and 11, 12 to resonate at f = 570MHz.
- Values measured with a Sony evaluation board.

Note1) Set the control voltage so that the output power becomes -15dBm under the conditions shown in the Electrical Characteristics Measurement Circuit. Input the two tone signals of 570kHz, 200mVp-p and 630kHz, 200mVp-p to I-IX; and also input to Q-QX the two tone signals whose phases are deviated by 90 degrees from those signals.

The ratio of the desired component and the 3rd order harmonic component of the outputs resulted from the above is measured, and the power level that is made by adding the half ratio to the desired component power level is labeled as the output IP3. See the figure on the next page.

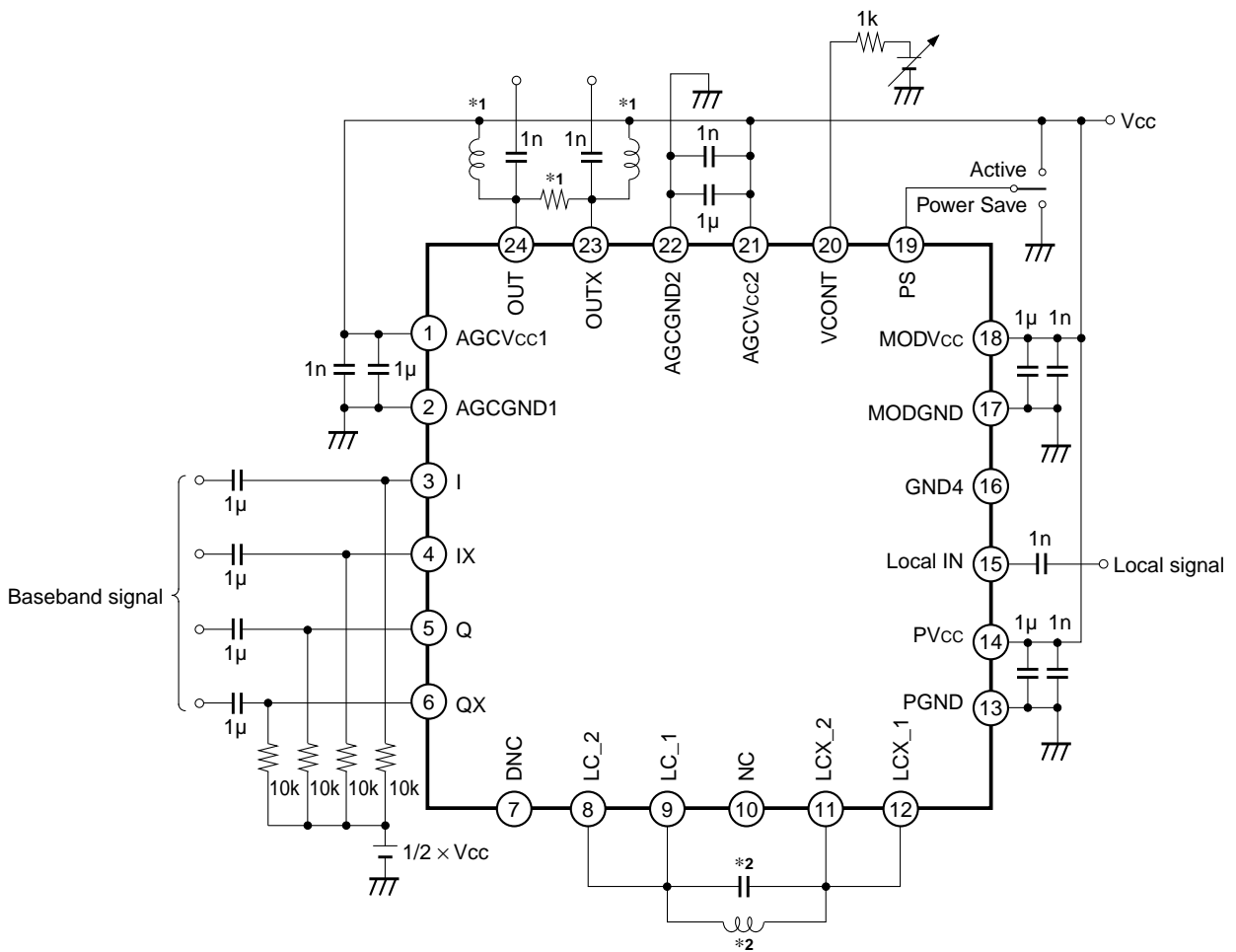


Electrical Characteristics Measurement Circuit



- \*1 LQN21A22NJ(K)04 (MURATA MFG. CO., LTD.)
- \*2 B5FL 616DS-1135 (TOKO, Inc.)
- \*3 LQN21A15NJ(K)04 (MURATA MFG. CO., LTD.)

Application Circuit



\*1 Adjust this value so that the impedance matching with this IC is optimum.

\*2 Adjust this value to resonate at the desired frequency.

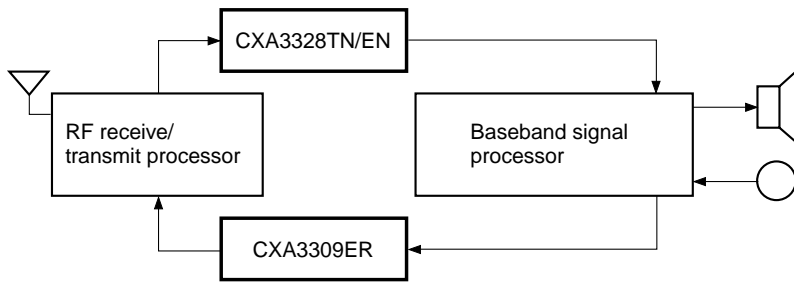
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**Description of Operation**

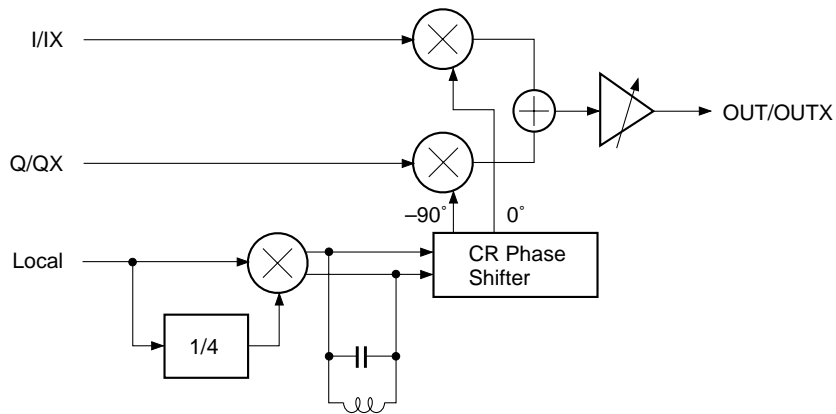
**1. Outline of operation**

This IC performs the signal processing between the analog transmit baseband processor block and the analog transmit RF processor block of the cellular phone. The figure below shows the general circuit block diagram for the portable cellular phones using this IC. The input for this IC is connected to the baseband signal processor block; the output is connected to the analog RF processor block.



**2. IC Internal Signal Flow**

Two baseband-processed signals I, Q and the local signal are input to this IC as shown in the figure below. The local signal itself and the local signal divided by 4 are multiplied, and then the unnecessary sideband products are eliminated using the external LC resonator. Also, that signal becomes the quadrature I/Q local signal via the CR phase shifter. The baseband I/Q signals are input to the quadrature modulator, and baseband processing to IF upconversion is performed with the quadrature local signals, it is input to the gain control amplifier, and output after the gain controlled to the necessary level.



## Notes on Operation

### 1. Baseband signal I/Q input

Pins 3 to 6, where the baseband signal is input, do not have a determined voltage internally on the IC. Therefore, a bias voltage equivalent to  $1/2V_{CC}$  should be applied externally.

### 2. Local signal

The local signal is generated from the components of  $3/4$  and  $5/4$  with regard to the local frequency, so connect the inductor and capacitor in parallel from Pins 8 and 9 to Pins 11 and 12 as a resonance filter to remove the unnecessary  $5/4$  signals. Also, the inductor and capacitor should be located as close to the pins as possible to minimize the series inductance for the pin connections.

### 3. IF signal output

The IF signal outputs, OUT/OUTX, are differential outputs. The output impedance should be  $1k\Omega$  including the external resistance with differential. Also, it is necessary to connect the inductor to eliminate the parasitic capacitance in the IC.

### 4. Notes on power supplies

The CXA3309ER is designed to operate by a 2.85V stabilized power supply to allow use with the battery driven portable phones. Using the multiple voltage regulators throughout the phone is recommended to minimize the power supply noise in the CXA3309ER power supply unit. The recommended power supply range for the CXA3309ER is from 2.7V to 3.3V. Decouple the power supplies around the CXA3309ER using  $1\mu\text{F}$  capacitor for each  $V_{CC}$  pin. Locate this capacitor as close to the pins as possible to minimize the series inductance. Using an additional  $1\text{nF}$  decoupling capacitor in parallel to the  $1\mu\text{F}$  capacitor is recommended to further reduce the high frequency noise in the power supply input to the CXA3309ER.

## Design Materials (Design Guarantee)

## Electrical Characteristics

(V<sub>CC</sub> = 2.7 to 3.8V, T<sub>a</sub> = -25 to +85°C)

Item	Symbol	Conditions	Measurement point	Min.	Typ.	Max.	Unit
<b>DC Characteristics</b>							
Current consumption 1	I <sub>max</sub>	V <sub>CONT</sub> = 2.85V	A	21.5	32	43	mA
Current consumption 2	I <sub>min</sub>	V <sub>CONT</sub> = 0V	A	17.5	26	32.5	
Power saving current	I <sub>ps</sub>	PS = low (in power saving mode)	A	—	—	5	μA
<b>AC Characteristics</b>							
Output IP3	OIP3	Note1	B	8.5	—	—	dBm
Output power 1	P <sub>O1</sub>	V <sub>CONT</sub> = 2.3V, differential output, f = 570MHz	B	-19	-15	-11	dBm
Output power 2	P <sub>O2</sub>	V <sub>CONT</sub> = 0.3V, differential output, f = 570MHz	B	-83	-77	-73	
Gain control range	G <sub>cr</sub>	V <sub>CONT</sub> = 0.3 to 2.3V, f = 570MHz	B	54	62	70	dB
Gain flatness	G <sub>flat</sub>	IF ± 2.5MHz	B	-0.25	0	0.25	dB
Output noise power 1	No <sub>1</sub>	P <sub>O</sub> = -25dB, I/Q inputs are no signal.	B	—	—	-147	dBm/ Hz
Output noise power 2	No <sub>2</sub>	P <sub>O</sub> = -65dBm, I/Q inputs are no signal.	B	—	—	-162	
I, Q residual sideband product	I <sub>mg</sub>	Suppression ratio of desired signal (f = 570 + 1) MHz and image signal (f = 570 - 1) MHz	B	—	—	-25	dBc
Carrier leak	CL	Ratio of desired signal (f = 570 + 1) MHz and local leak (f = 570) MHz	B	—	—	-18	
Input I/Q phase error	IQ <sub>PE</sub>	Input signal I/Q phase difference -90° when the output signal I/Q phase difference is 90°.	B	-3	0	3	deg
Input I/Q gain error	IQ <sub>GE</sub>	I/Q input signal level difference when output signal I/Q levels are the same.	B	-2.5	0	2.5	dB
Error vector magnitude	EVM		B	—	—	3	%
Response time	T <sub>r</sub>	Until output rise of 90% after the power is turned ON.	B	—	—	10	μs

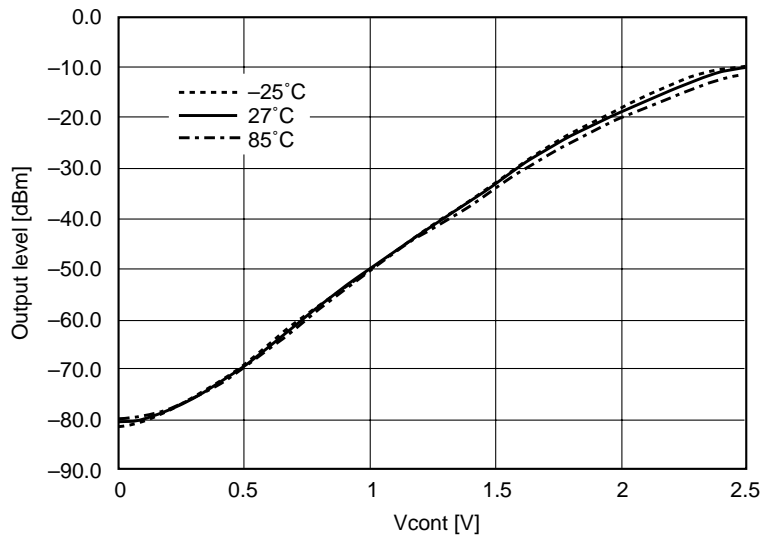
- Unless otherwise specified, the I/Q baseband input signals and local input signal use the conditions shown in the Electrical Characteristics Measurement Circuit and the control voltage and power saving pins are set to V<sub>CONT</sub> = 2.3V, PS = high.
- IF output impedance is 1kΩ.
- Set the L, C values between Pins 8, 9 and 11, 12 to resonate at f = 570MHz.
- Values measured with a Sony evaluation board.

**Input Impedance**

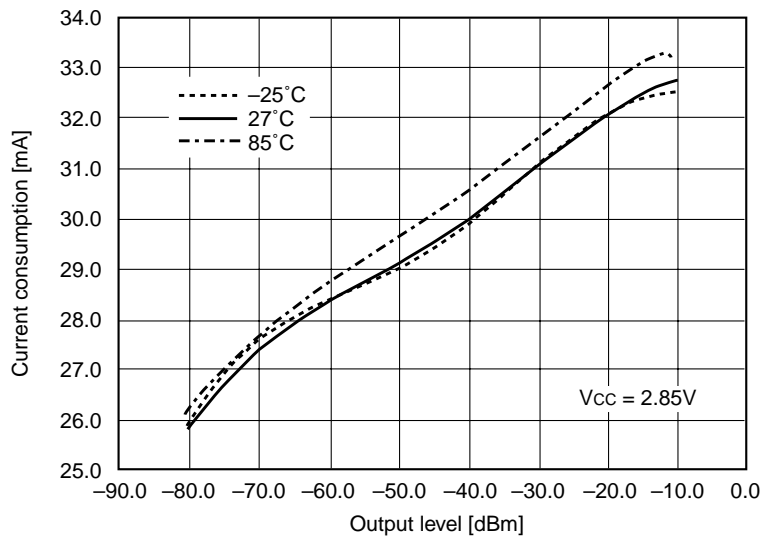
Item	Symbol	Conditions	Measurement point	Min.	Typ.	Max.	Unit
I/Q input resistance	R <sub>IQ</sub>	Single	3, 4, 5, 6	60	85	—	kΩ
I/Q input capacitance	C <sub>IQ</sub>	Single	3, 4, 5, 6	—	—	10	pF
VCONT pin input resistance	R <sub>vc</sub>		20	10	—	—	kΩ
Local IN input resistance	R <sub>L</sub>		15	37.5	50	62.5	Ω

Example of Representative Characteristics

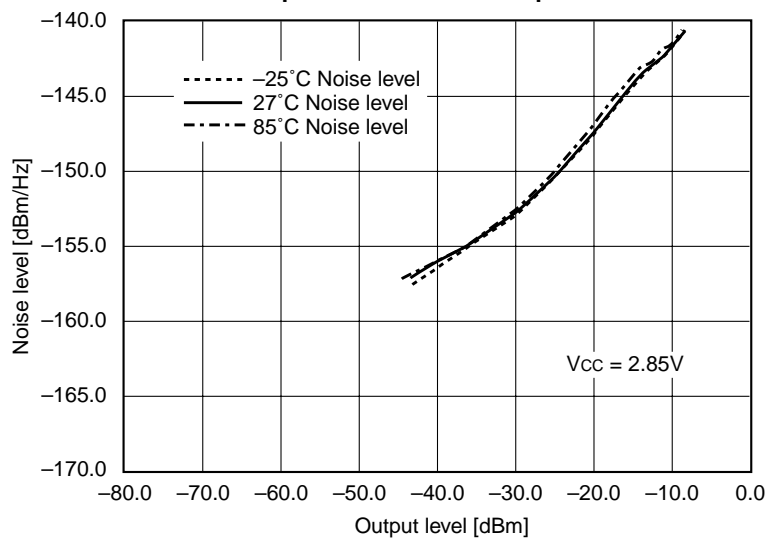
Output level vs. Vcont

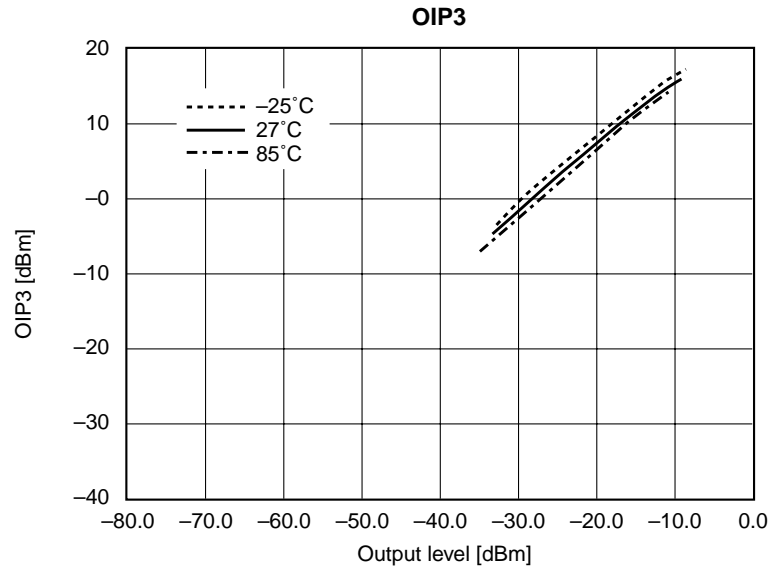


Current consumption vs. Output level



Output noise level vs. Output level

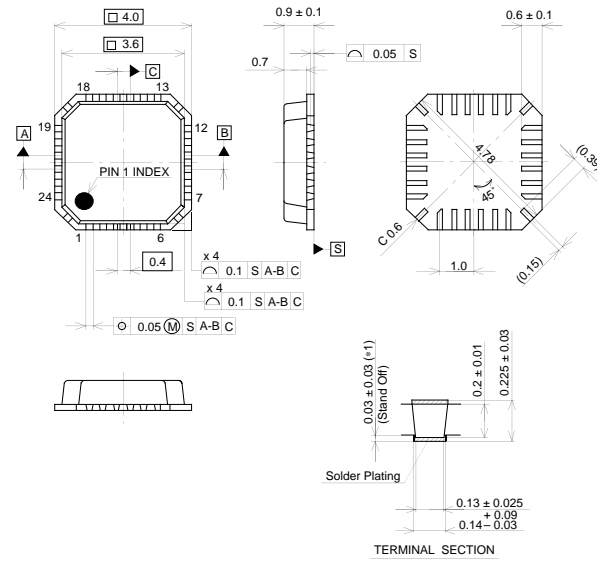




Package Outline

Unit: mm

24PIN VQFN(PLASTIC)

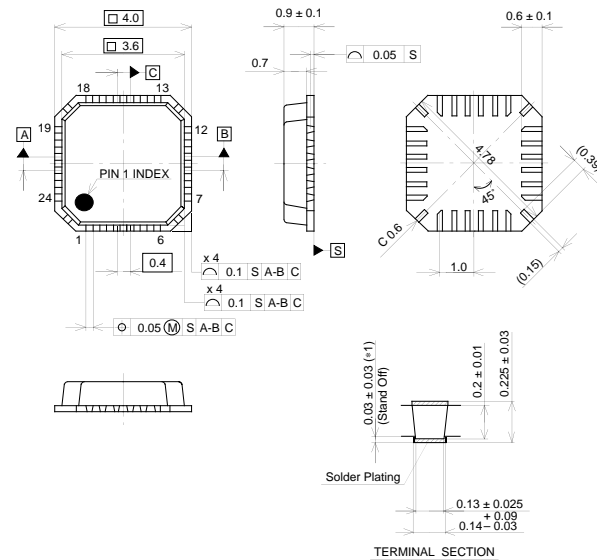


SONY CODE	VQFN-24P-03
EIAJ CODE	_____
JEDEC CODE	_____

PACKAGE STRUCTURE	
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.04g

Kokubu & SCT Ass'y

24PIN VQFN(PLASTIC)



SONY CODE	VQFN-24P-03
EIAJ CODE	_____
JEDEC CODE	_____

PACKAGE STRUCTURE	
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.04g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	COPPER ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18μm